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(12) United States Design Patent

LiCalzi et al.

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(54) **INSTRUMENT MODULE**

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(**) Term: **15 Years**

(21) Appl. No.: **29/569,385**

(22) Filed: **Jun. 27, 2016**

(51) **LOC (10) Cl.** **24-01**

(52) **U.S. Cl.**
USPC **D24/216**

(58) **Field of Classification Search**
USPC D24/216, 111, 127, 107, 169, 186, 217, D24/219, 223–224, 231–234; D10/46, D10/70, 81, 97; 422/1, 62–65, 67, 68.1, 422/70, 81, 129, 500, 506, 561, 422/FOR. 106; 435/287.1, 287.3; 436/43, 45, 47; 600/300, 301, 368, 372, 600/481, 529, 544, 554, 561; 607/4, 5, 9, 607/30
CPC ... G01R 31/31907; B04B 13/00; B04B 15/00; B04B 2005/0435; B04B 5/0421; A61B 5/157; G06F 19/366; B01D 21/262
See application file for complete search history.

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Primary Examiner — Wan Laymon
Assistant Examiner — Mark Booker

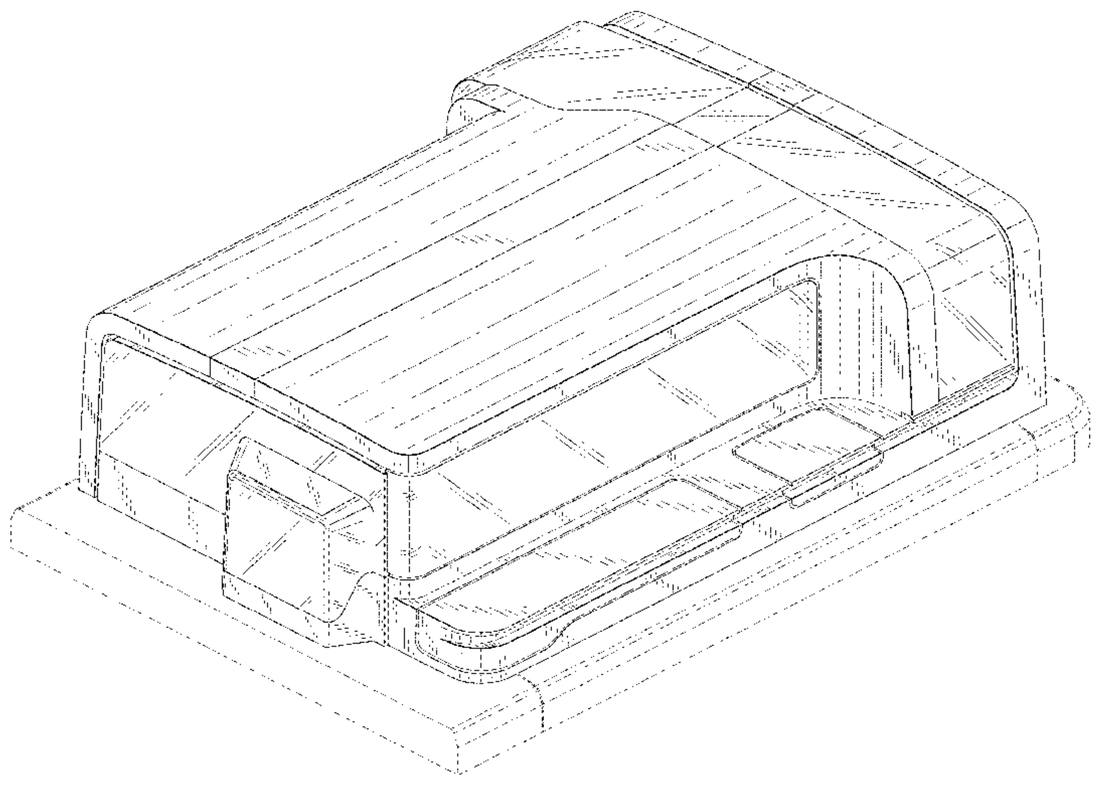
(57) **CLAIM**

The ornamental design for an instrument module, as shown and described.

DESCRIPTION

FIG. **1** is a front perspective view of an instrument module in accordance with an embodiment;
FIG. **2** is a rear perspective view of an instrument module in accordance with an embodiment;
FIG. **3** is a front elevational view of an instrument module in accordance with an embodiment;
FIG. **4** is a rear elevational view of an instrument module in accordance with an embodiment;
FIG. **5** is a left side elevational view of an instrument module in accordance with an embodiment;
FIG. **6** is a right side elevational view of an instrument module in accordance with an embodiment;
FIG. **7** is a top view of an instrument module in accordance with an embodiment; and,
FIG. **8** is a bottom view of an instrument module in accordance with an embodiment.
The broken lines shown in the figures represent portions of the instrument module that form no part of the claimed design.

1 Claim, 8 Drawing Sheets



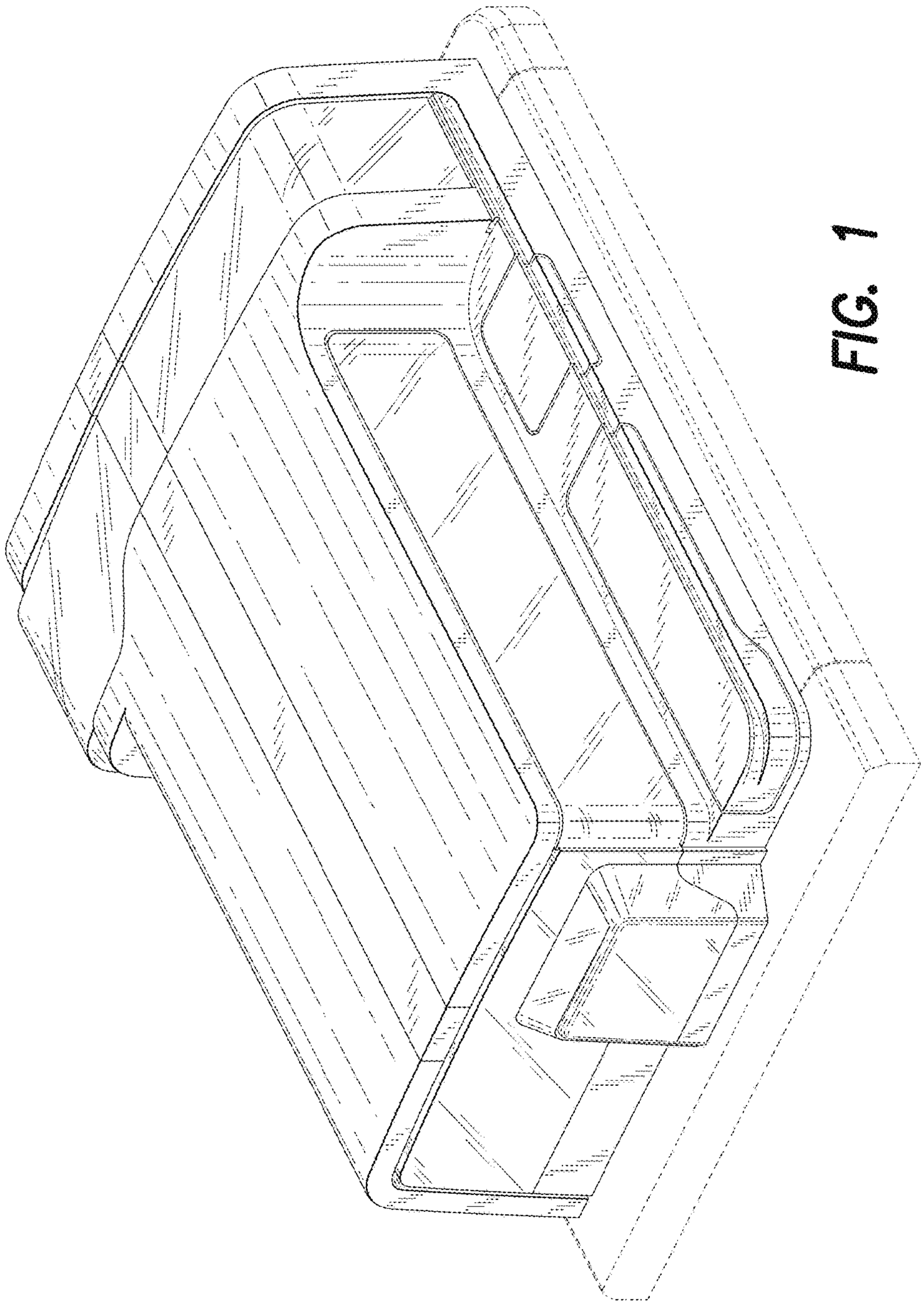


FIG. 1

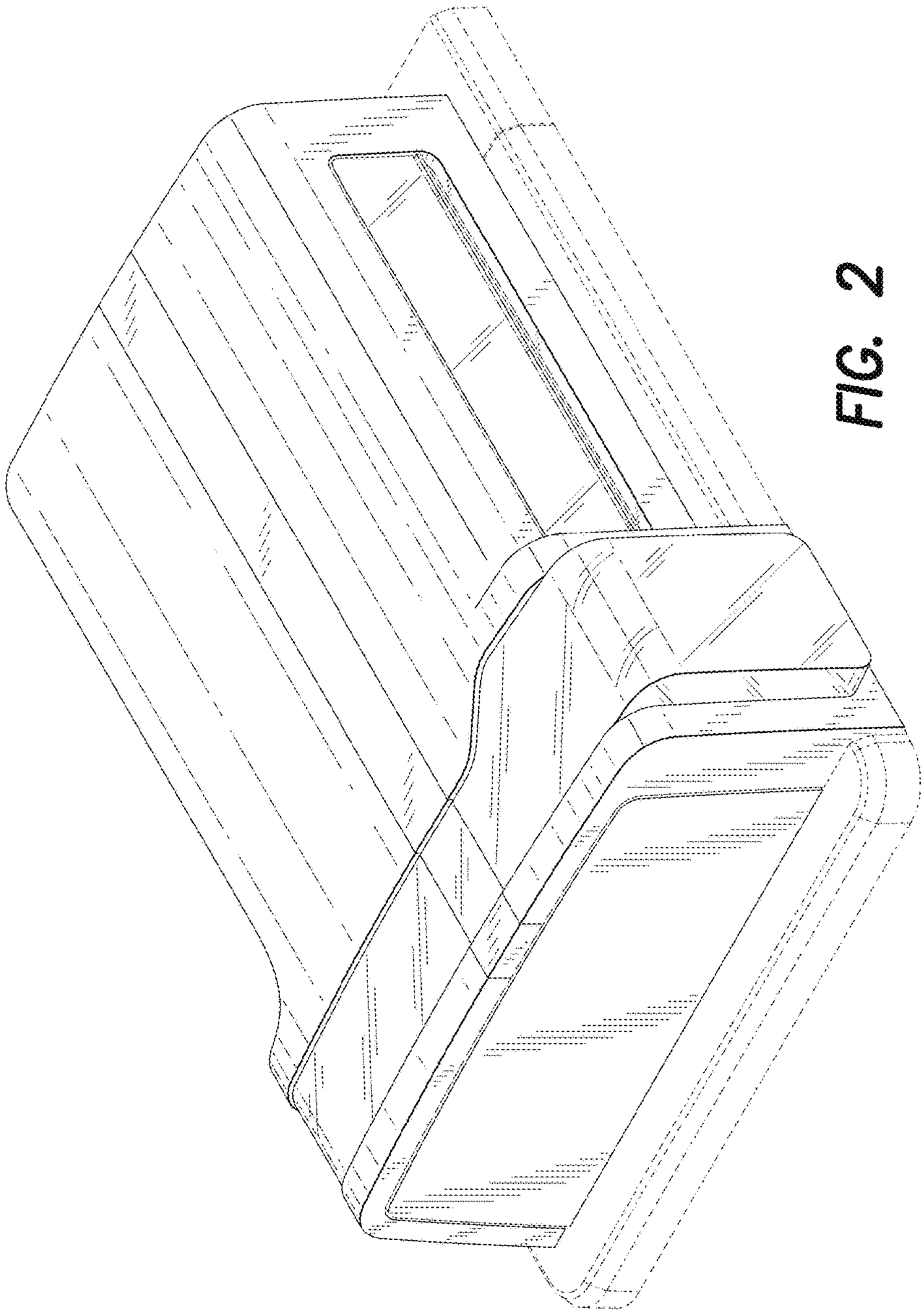


FIG. 2

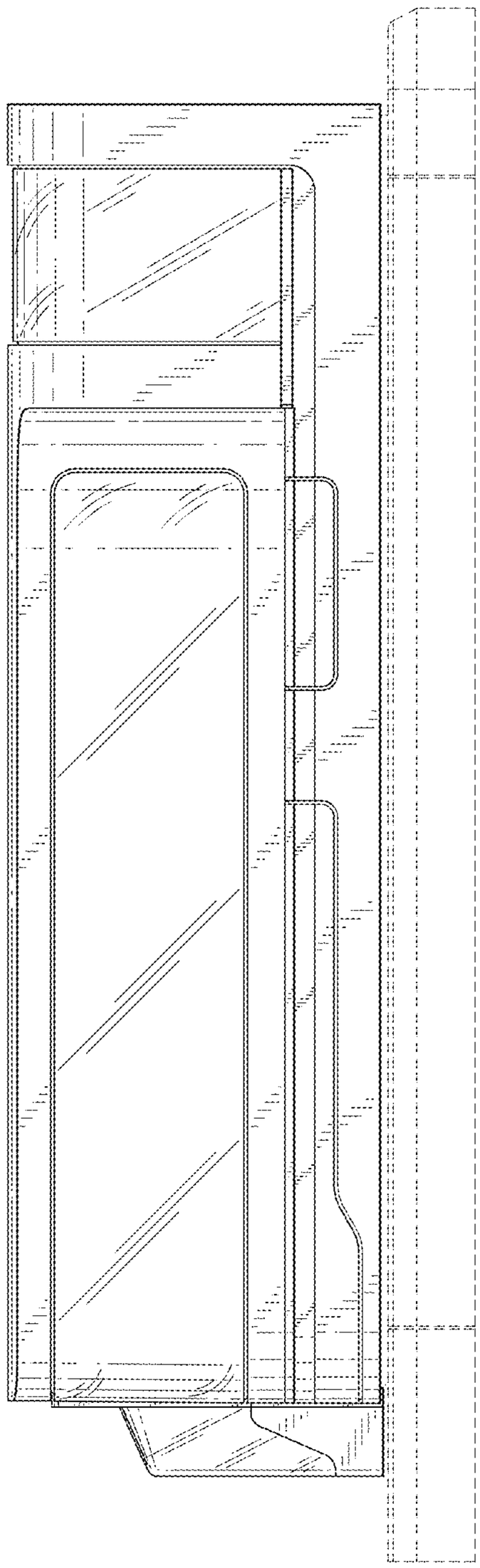


FIG. 3

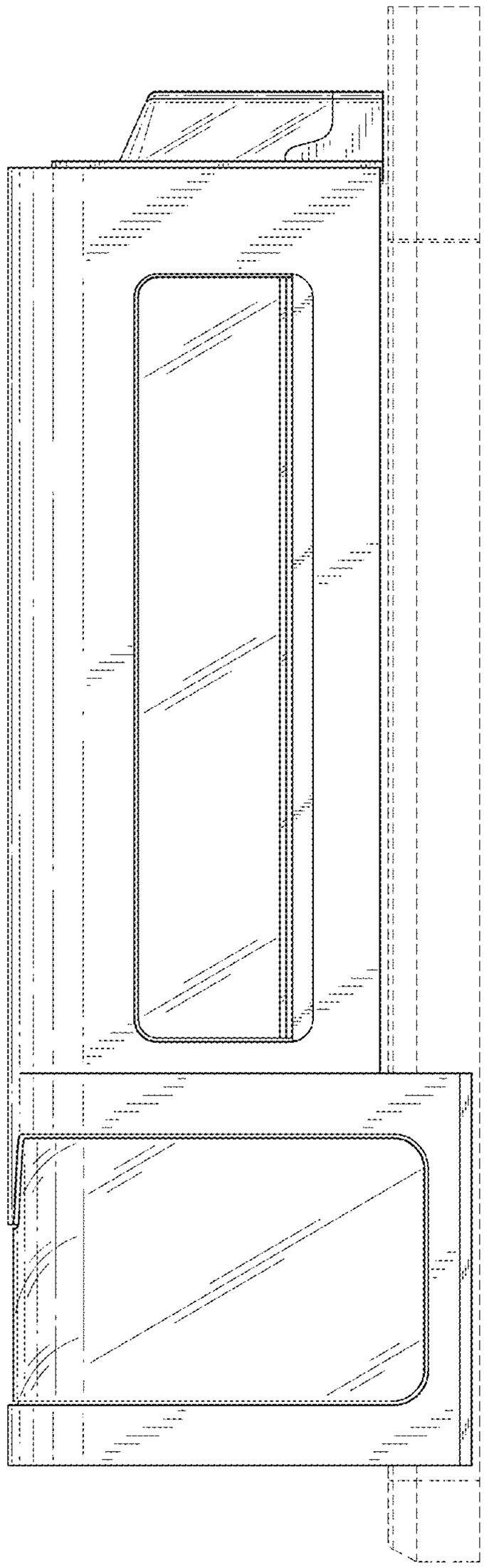


FIG. 4

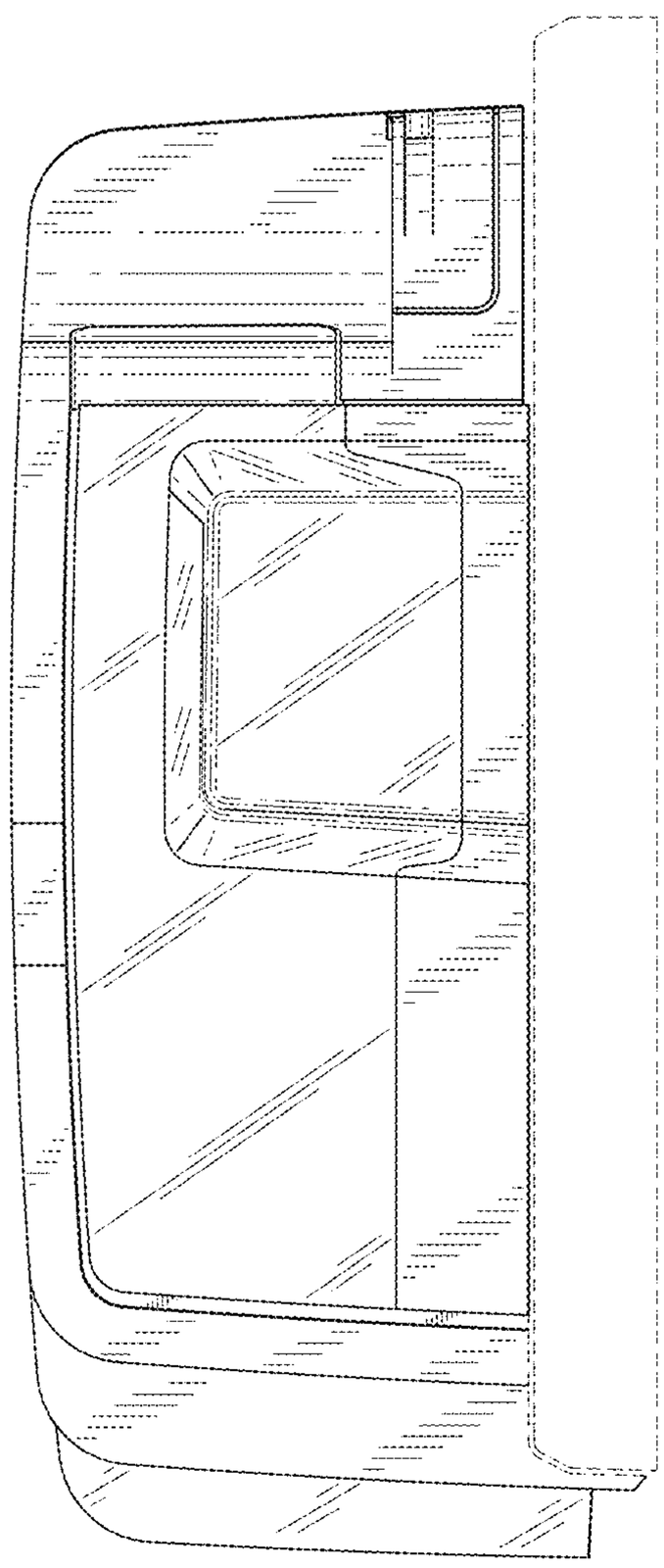


FIG. 5

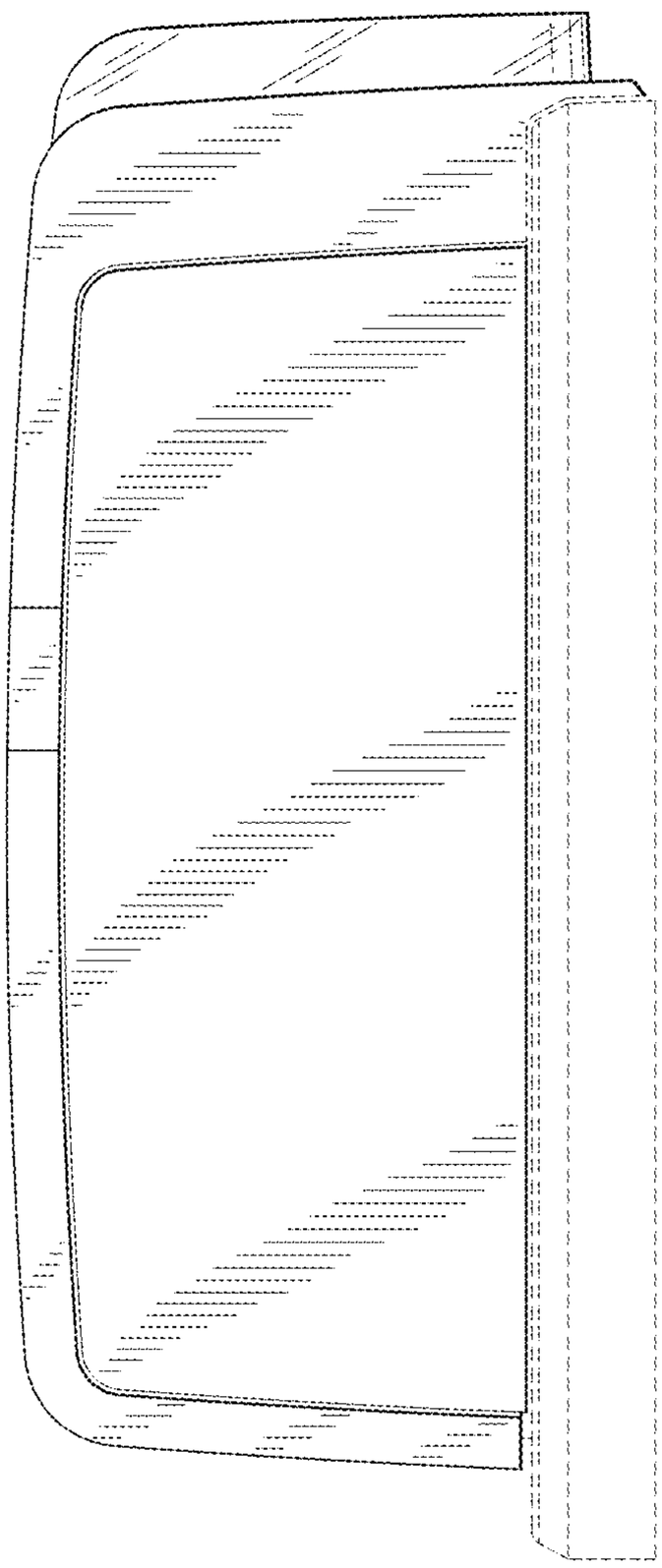


FIG. 6

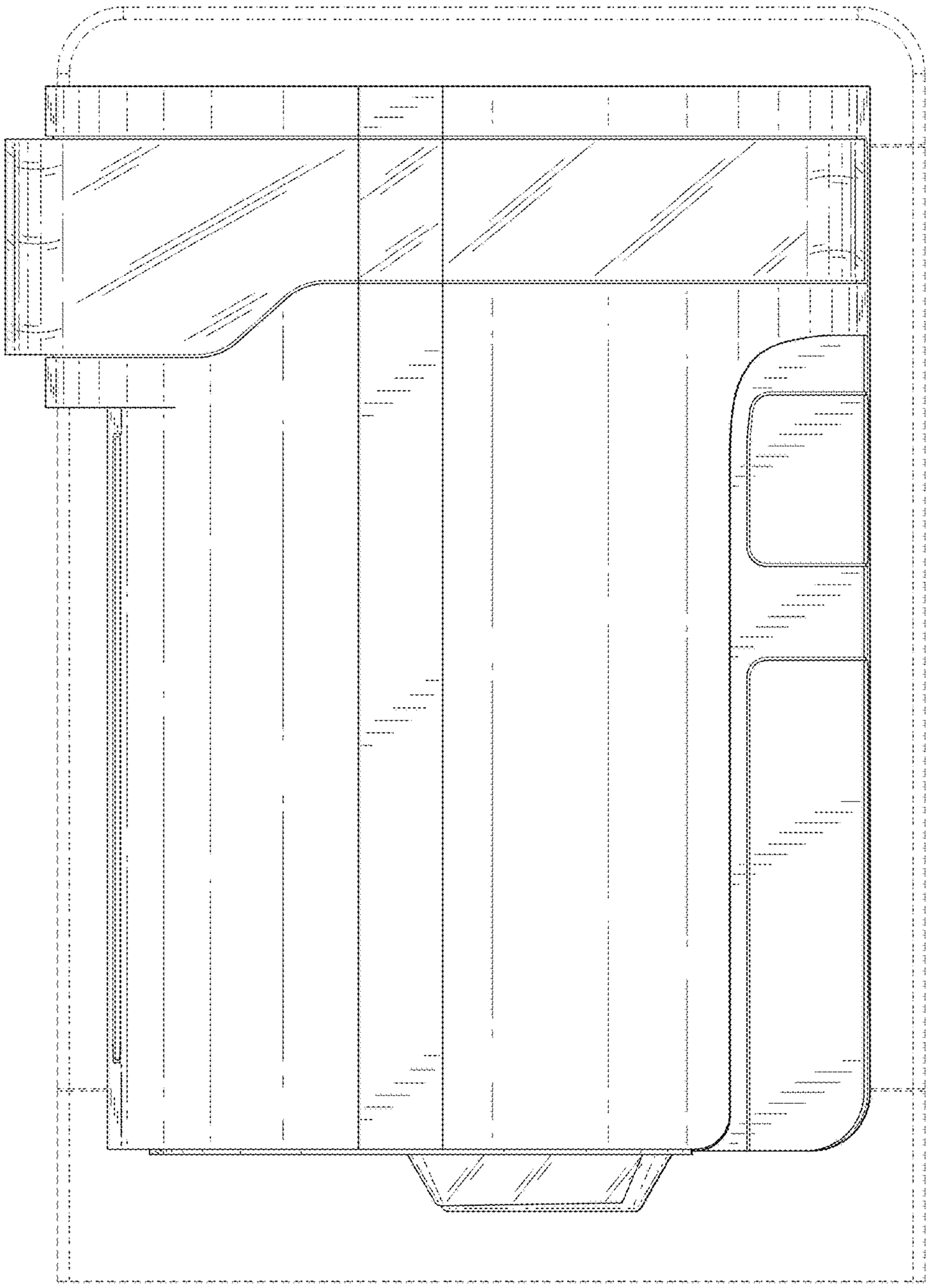


FIG. 7

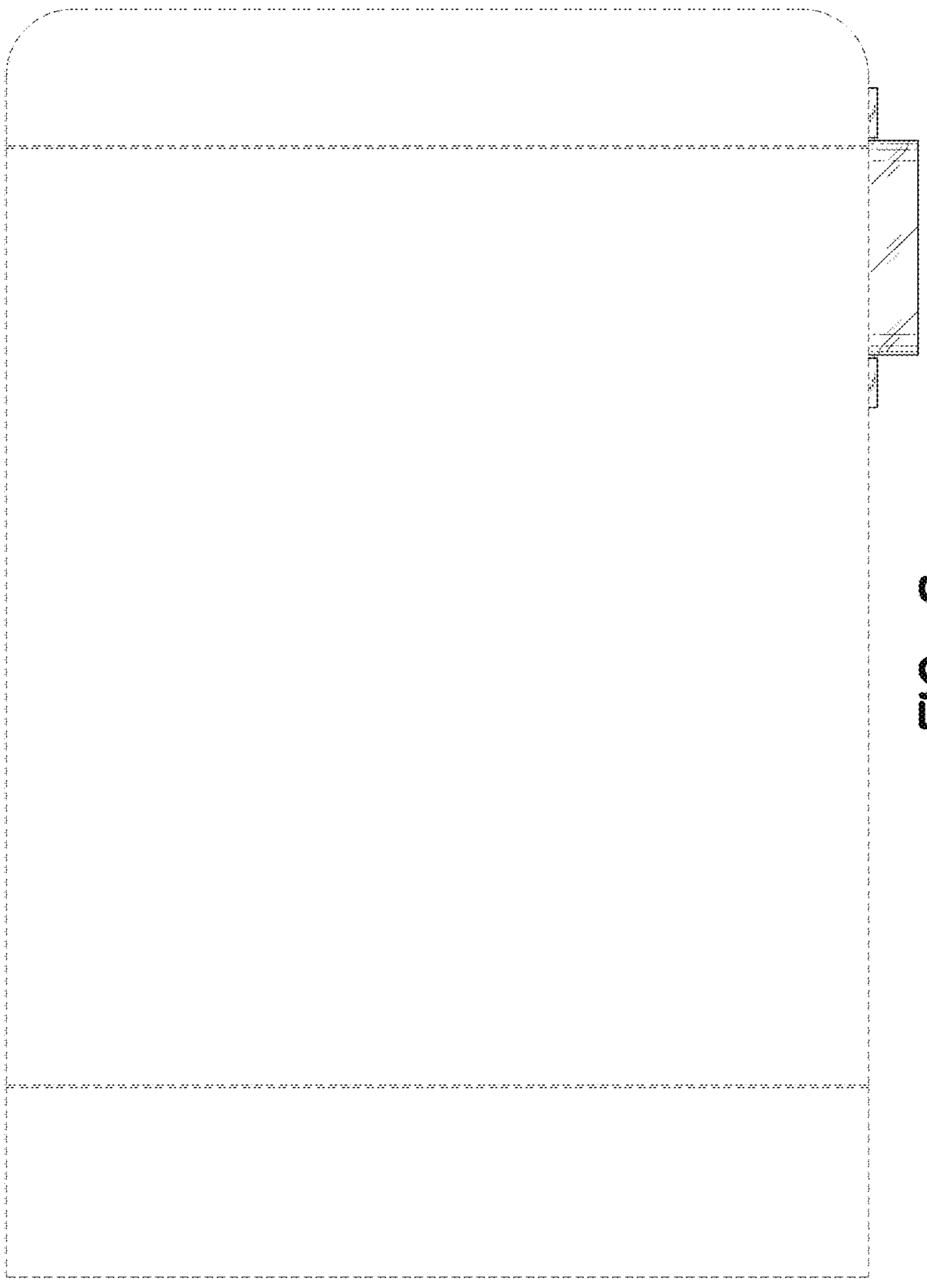


FIG. 8